User's Guide
SLVUAJ1F–November 2015–Revised May 2018

TPS65917-Q1 User's Guide to Power DRA7xx and TDA2x/TDA2Ex

This User's Guide can be used as a guide for integrating the TPS65917-Q1 power-management integrated circuit (PMIC) into a system powering the DRA72x, DRA74x, DRA75x, TDA2x, or TDA2Ex device.

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Trademarks

1 Introduction

This user's guide can be used as a guide for connectivity between the TPS65917-Q1 PMIC and a processor. This guide describes the platform connections as well as the power-up, power-down, and sleep entry and exit sequences along with the OTP configurations. In addition, this user's guide describes the initialization software and advises how to get started with the TPS65917-Q1 PMIC. This document does not provide details about the power resources, external components, or the functionality of the device. For such information, see the TPS65917-Q1 data sheet, *TPS65917-Q1 Power Management Unit (PMU) for Processor*. The TPS65917-Q1 is optimized to power DRA72x and TDA2Ex. When using TPS65917-Q1 to power the other processors, the user should make sure that the power requirements of the processor do not exceed the current capabilities of the TPS65917-Q1 device.

In the event of any inconsistency between the official specification and any user's guide, application report, or other referenced material, the data sheet specification will be the definitive source.

2 Device Versions

Four different versions of the TPS65917-Q1 device are available and the OTP settings for each version are described in this document. The three different versions of the device can be used to power the DRA7xx and TDA2x/TDA2Ex processor devices. The OTP version can be read from the SW_REVISION register. In this guide, each device version is distinguished either by the part number or the SW_REVISION value which are both listed in Table 1.

Texas Instruments recommends having 15% margin in the load current. Therefore the current requirements listed in Table 1 are 15% lower than the maximum capability of the regulator.

Table 1. TPS65917-Q1 OTP Settings Differentiation

LOAD CURRENT REQUIREMENT(1)	GPIO_6 FUNCTION	ORDERABLE PART NUMBER	CONTENT OF SW_REVISION REGISTER
DSPEVE + GPU + IVA < 2.55 A	POWERGOOD	O917A130TRGZRQ1	0x30
DSPEVE + GPU + IVA < 2.55 A	NSLEEP	O917A131TRGZRQ1	0x31
DSPEVE + GPU + IVA < 3 A	POWERGOOD	O917A132TRGZRQ1	0x32
DSPEVE + GPU + IVA < 3 A	NSLEEP	O917A133TRGZRQ1	0x33

(1) The load current must only be considered when powering Jacinto 6. All four OTP options can power the maximum performance of the Jacinto 6 Eco (DRA72x and TDA2Ex) devices.

All four OTP configurations are capable of powering the DRA72x and TDA2Ex devices, or powering the DRA74x, DRA75x, and TDA2x devices with DSPEVE + GPU + IVA < 2.55 A. In this case, select the 0x30 or 0x31 configurations because they have the same power mapping as the DRA72x EVM.

3 Platform Connection

Figure 1 shows the detailed connections between a processor and the O917A130TRGZRQ1 or O917A131TRGZRQ1. Both devices use the same power configuration, and it is the same configuration used on the DRA72x and TDA2Ex EVM. If VIO_IN of the PMIC should be 1.8 V, it could be supplied by SMPS4. If VIO_IN of the PMIC should be 3.3 V, it could be supplied by the switched 3.3-V output of the TPS22965-Q1 device. When using DDR self-refresh mode, VIO_IN must be supplied before GPIO_4 is enabled in the power sequence but must ramp after VCC is stable. In this case, VIO_IN should be an external supply, either enabled externally or by an early signal such as SMPS4. When DDR self-refresh mode is not used, the load switch enabled by GPIO_4 is not required.

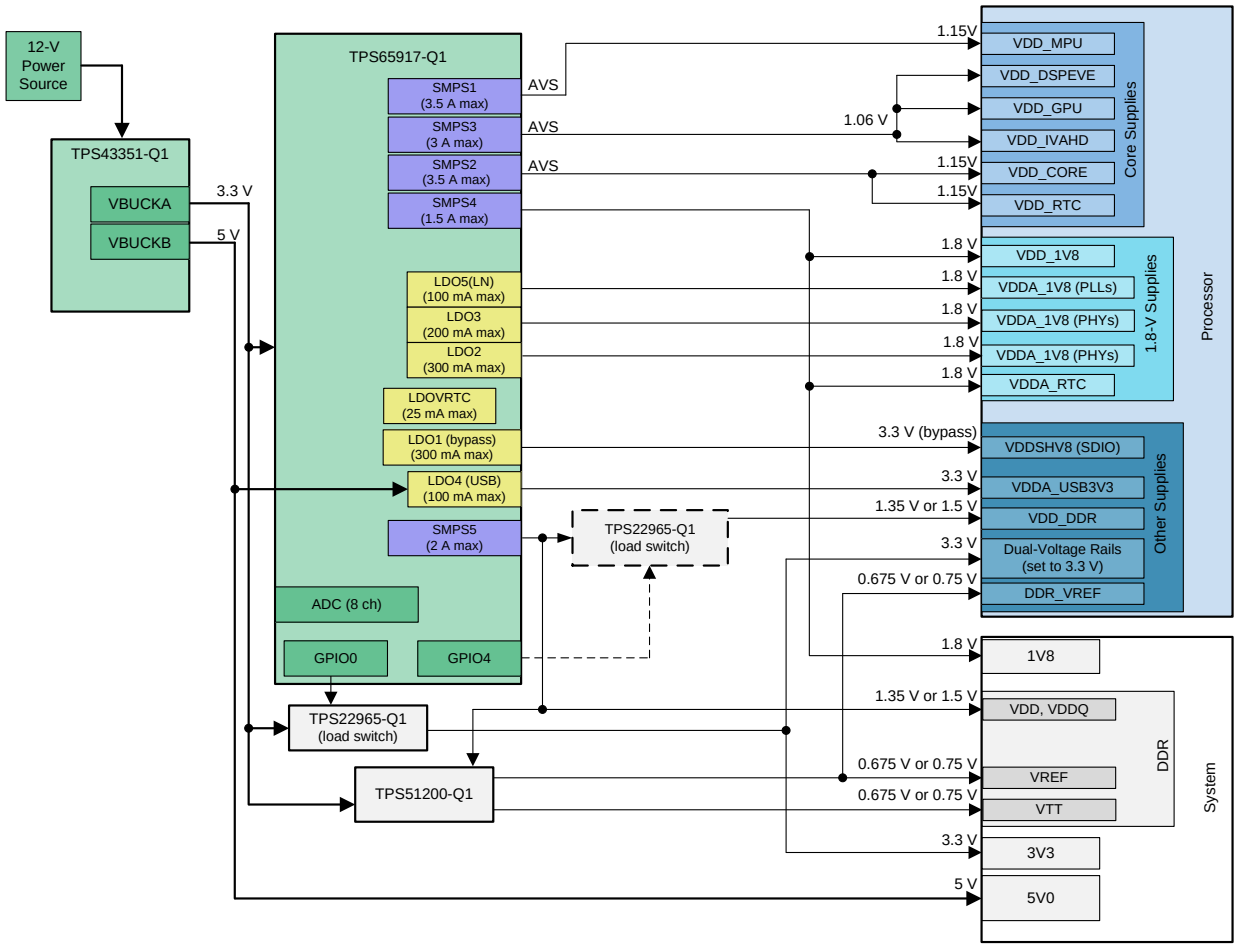

Figure 1. Processor Connection With O917A130TRGZRQ1 or O917A131TRGZRQ1

Figure 2 shows the detailed connections between the processor and the O917A132TRGZRQ1 or O917A133TRGZRQ1. Compared to the previous configuration, this configuration swaps SMPS2 and SMPS3 which provides a higher current capacity for the DSPEVE/GPU/IVA domains. When using DRA74x/75x or TDA2x, this configuration is recommended because of the higher current capacity on those domains. If VIO_IN of the PMIC should be 1.8 V, it could be supplied by SMPS4. If VIO_IN of the PMIC should be 3.3 V, it could be supplied by the switched 3.3-V output of the TPS22965-Q1 device. When using DDR self-refresh mode, VIO_IN must be supplied before GPIO_4 is enabled in the power sequence but must ramp after VCC is stable. In this case, VIO_IN should be an external supply, either enabled externally or by an early signal such as SMPS4. When DDR self-refresh mode is not used, the load switch enabled by GPIO_4 is not required.

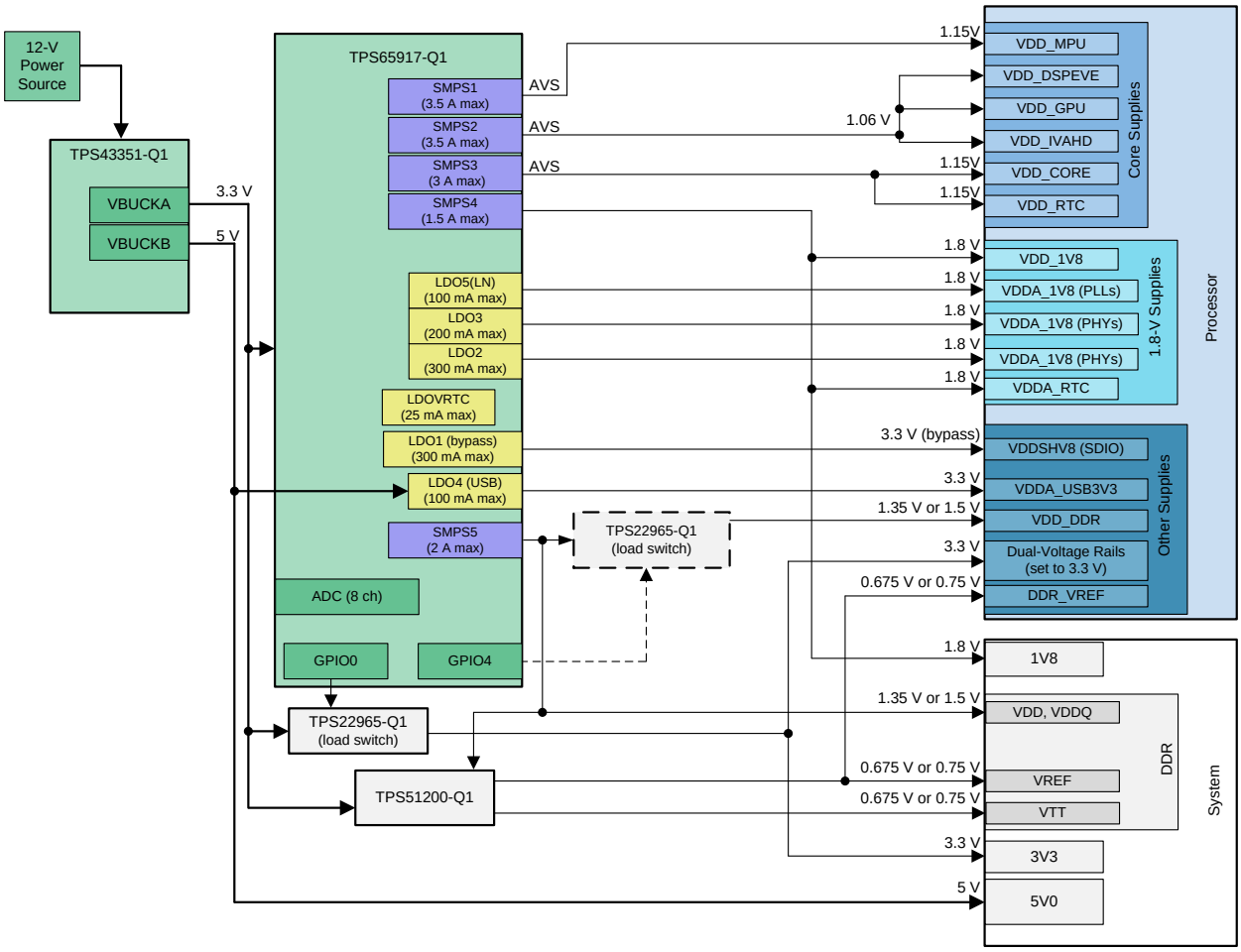

Figure 2. Processor Connection With O917A132TRGZRQ1 or O917A133TRGZRQ1

In both configurations, LDO2 and LDO3 are used to supply the PHY domains. Table 2 describes how the PHY domains should be split between the two LDOs.

Table 2. LDO2 and LDO3 Mapping to PHY Domains

TPS65917-Q1 LDO	PROCESSOR BALL	VOLTAGE RAIL (DRA74x/DRA75x/TDA2x)	VOLTAGE RAIL (DRA72x/TDA2Ex)
LDO3 (200 mA)	AA13	VDDA_USB1	VDDA_USB1
	AB12	VDDA_USB2	VDDA_USB2
	W12	VDDA_USB3	VDDA_CSI2
	V13	VDDA_SATA	VDDA_SATA
LDO2 (300 mA)	Y17	VDDA_HDMI	VDDA_HDMI
	W14	VDDA_PCIE	VDDA_USB3
	AA17	VDDA_PCIE0	VDDA_PCIE
	AA16	VDDA_PCIE1	VDDA_PCIE0

Figure 3 and Figure 4 show the reset connections required between the TPS65917-Q1 and the processor. All of the OTP configurations have the same reset connections to the processor, along with one of the two options for enabling the power supply; either POWERHOLD or PWRON. Enabling either of these signals turns on the TPS65917-Q1 device and starts the startup sequence for the processor. Figure 3 shows the POWERHOLD configuration for the TPS65917-Q1 and the processor. GPIO_5 is configured as POWERHOLD in the OTP memory. To turn on the TPS65917-Q1, GPIO_5 must be set to a high logic level. When using POWERHOLD, the PWRON signal can be left floating.

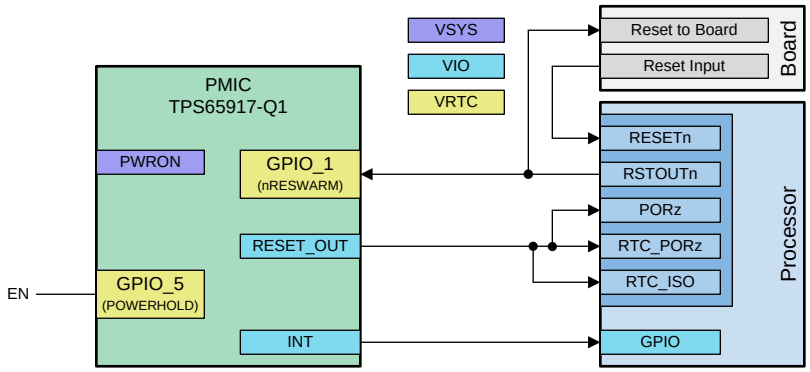

Figure 3. Reset Connections With POWERHOLD Configuration

Figure 4 shows the PWRON configuration for the TPS65917-Q1 and the processor. This configuration is used when a push button enables the system. As shown, PWRON is connected to a switch that pulls PWRON to a low logic level when the switch is pressed on.

In some applications, a warm reset is required. This allows for the TPS65917-Q1 to reset to its default settings without turning off first. To complete a warm reset correctly, POWERHOLD must be kept at a high logic level so the TPS65917-Q1 does not turn off. One solution for this scenario is that GPIO_5 is tied to GPIO_2 and pulled up to VIO. Pulling GPIO_5 to VIO ensures that POWERHOLD is kept high during a warm reset. Tying GPIO_2 to POWERHOLD provides a method to set POWERHOLD low, which is necessary to turn off the device.

For this solution to work, a few software writes must occur:

1. First, enable the TPS65917-Q1 by the push button.
2. Second, set GPIO_2 to a high logic level.
3. Third, set GPIO_2 as an output.

When ready to disable the TPS65917-Q1, set GPIO_2 to a low logic level.

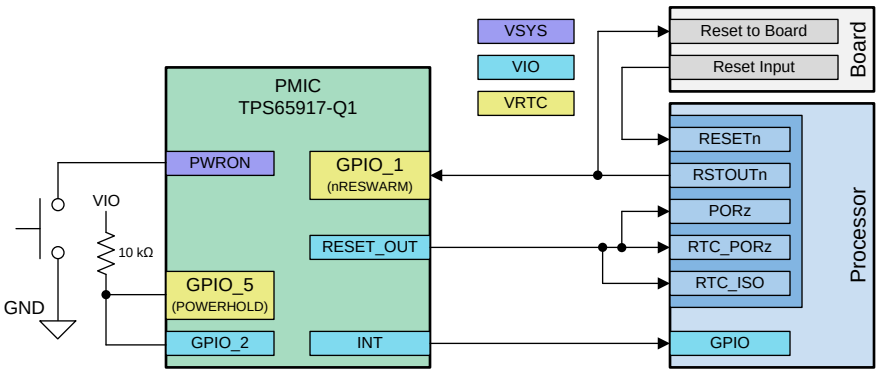

Figure 4. Reset Connections With PWRON Configuration

4 BOOT OTP Configuration

All TPS65917-Q1 resource settings are stored in the form of registers. Therefore, all platform-related settings are linked to an action altering these registers. This action can be a static update (register initialization value) or a dynamic update of the register (either from the user or from a power sequence).

Resources and platform settings are stored in nonvolatile memory (OTP). These settings are defined as follows:

Static platform settings — These settings define, for example, SMPS or LDO default voltages, and GPIO functionality. Most static platform settings can be overwritten by a power sequence or by the user.

Sequence platform settings — These settings define the TPS65917-Q1 power sequences between state transitions, such as the OFF2ACT sequence when transitioning from OFF mode to ACTIVE mode. The power sequence is composed of several register accesses that define which resources (and the corresponding registers) must be updated during the respective state transition. The state of these resources can be overwritten by the user after the power sequence completes execution.

5 Static Platform Settings

Each device has predefined values stored in OTP which control the default configuration of the device. The tables in this section list the OTP-programmed values for each device, distinguished by the SW_REVISION.

5.1 System Voltage Monitoring

Table 3. System Voltage Monitoring OTP Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE	UNIT
VSYS_MON	VSYS_HI	System voltage rising-edge threshold	3.1	V
VSYS_LO	VSYS_LO	System voltage falling-edge threshold	2.75	V

Comparators that monitor the voltage on the VCC_SENSE, and VCCA pins control the power state machine of the TPS65917-Q1 device. For electrical parameters, refer to the data sheet.

POR— When the supply at the VCCA pin is below the POR threshold, the TPS65917-Q1 device is in the NO SUPPLY state. All functionality is off. The device moves from the NO SUPPLY state to the BACKUP state when the voltage in VCCA rises above the POR threshold.

VSYS_LO— When the voltage on the VCCA pin rises above VSYS_LO, the device enters from the BACKUP state to the OFF state. When the device is in an ACTIVE, SLEEP, or OFF state and the voltage on VCCA decreases below the VSYS_LO level, the device enters backup mode. The level of VSYS_LO is OTP programmable.

VSYS_MON— During power up, the value of VSYS_HI OTP is used as a threshold for the VSYS_MON comparator which is gating PMIC start-up (that is, as a threshold for transition from the OFF state to the ACTIVE state). The VSYS_MON comparator monitors the VCC_SENSE pin. After power up, software can configure the comparator threshold in the VSYS_MON register.

VBUS_DET— The VBUS_DET comparator is monitoring the VBUS_SENSE (secondary function of GPIO1) pin. This comparator is active when VCCA is greater than the POR threshold. Triggering the threshold level generates an interrupt. It can wake up the device from the SLEEP state, but can also switch on the device from the OFF state.

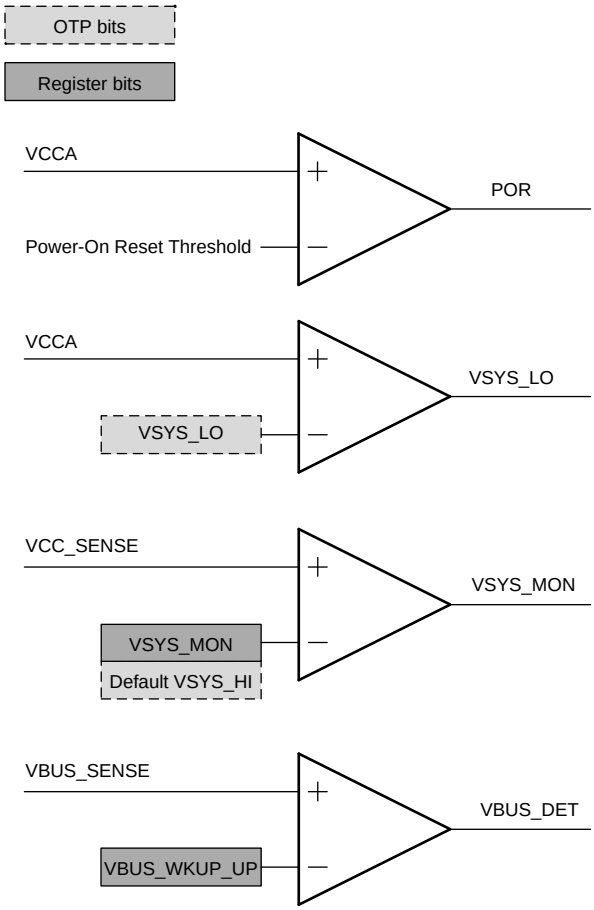

Figure 5. PMIC Comparators

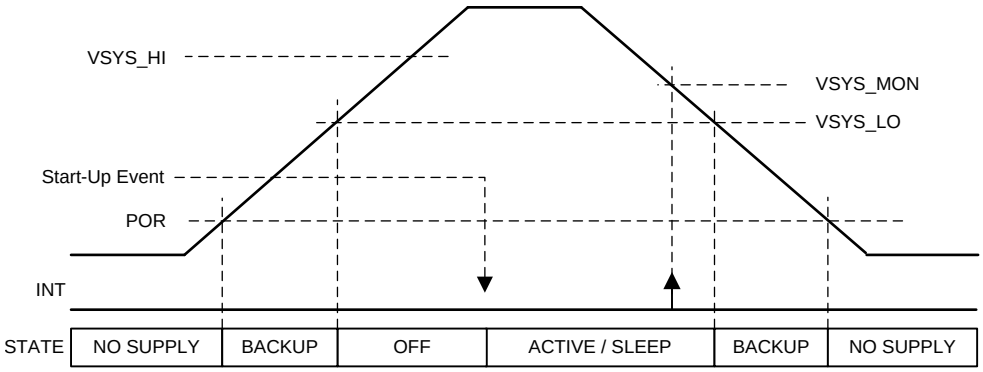

Figure 6. State Transitions

NOTE: The maximum input voltage of the VCC_SENSE pin depend on the OTP setting of PMU_CONFIG [HIGH_VCC_SENSE] as listed in the *Recommended Operating Conditions* table of the TPS65917-Q1 data sheet. This configuration is set as HIGH_VCC_SENSE = 0 with the VCC_SENSE and pins are connected to VCCA.

For the recommended operating conditions of the electrical parameters, see the TPS65917-Q1 data sheet, *TPS65917-Q1 Power Management Unit (PMU) for Processor*.

5.2 SMPS

This section describes the default voltage for each SMPS. Both options have two default voltages for SMPS5 based on the connection of the BOOT pin. If the BOOT pin is connected to 0 V, then SMPS5 defaults to 1.35 V. If the BOOT0 pin is connected to 1.8 V, then SMPS5 outputs 1.5 V.

Table 4. SMPS OTP Settings

BIT	DESCRIPTION [1]	0x30, 0x31 VALUE		0x32, 0x33 VALUE		UNIT
		BOOT = 0	BOOT = 1	BOOT = 0	BOOT = 1	
SMPS1_VOLTAGE	Default output voltage for the regulator	1.15				V
SMPS2_VOLTAGE	Default output voltage for the regulator	1.15		1.06		V
SMPS3_VOLTAGE	Default output voltage for the regulator	1.06		1.15		V
SMPS4_VOLTAGE	Default output voltage for the regulator	1.80				V
SMPS5_VOLTAGE	Default output voltage for the regulator	1.35	1.50	1.35	1.50	V
SMPS1_SMPS12_EN	SMPS12 single-phase or dual-phase configuration. 0: SMPS1 and SMPS2 single-phase 1: SMPS12 dual-phase	0				NA

(1) The regulator output voltage cannot be modified while active from one (0.7 to 1.65 V) voltage range to the other (1 to 3.3 V) voltage range or the other way around. The regulator must be turned off to do so.

5.3 LDO

This section describes the default output voltage for each LDO. Note that by default LDO1 is in bypass mode, which means its output is equal to its input. Typically, LDO1 would be supplied by a 3.3V supply from a pre-regulator or from the switched 3.3V output of the load switch enabled by GPIO_0.

Table 5. LDO OTP Settings

BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE	UNIT
LDO1_VOLTAGE	Default output voltage for the regulator	BYPASS	V
LDO2_VOLTAGE	Default output voltage for the regulator	1.8	V
LDO3_VOLTAGE	Default output voltage for the regulator	1.8	V
LDO4_VOLTAGE	Default output voltage for the regulator	3.3	V
LDO5_VOLTAGE	Default output voltage for the regulator	1.8	V

NOTE: LDO1 and LDO2 share a single input LDO12_IN and must by supplied by the same voltage. Refer to the input voltage parameter in the data sheet.

5.4 Interrupts

The interrupts are split into four register groups (INT1, INT2, INT3, and INT4). All interrupts are logically combined on a single output line, INT (default active-low). This line is used as an external interrupt line to warn the host processor of any interrupt event that has occurred within the device. The OTP settings in this section show whether each interrupt is enabled or disabled by default.

Table 6. INT1 OTP Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE
INT1_MASK	VSYS_MON	Enable and disable interrupt from the VSYS_MON comparator	1: Interrupt generation disabled
	PWRDOWN	Enable and disable interrupt from the PWRDOWN pin	0: Interrupt generated
	PWRON	Enable and disable interrupt from PWRON pin. A PWRON event is always an ON request.	1: Interrupt generation disabled
	LONG_PRESS_KEY	Enable and disable interrupt from long key press on the PWRON pin	1: Interrupt generation disabled
	HOTDIE	Enable and disable interrupt from device hot-die detection. The interrupt can be used as a pre-warning for processor to limit the PMIC load, before increasing die temperature forces shutdown.	0: Interrupt generated

Table 7. INT2 OTP Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE
INT2_MASK	SHORT	Triggered from internal event of SMPS or LDO outputs failing. If an interrupt is enabled, it is an ON request.	0: Interrupt generated
	WDT	Enable and disable interrupt from watchdog expiration	0: Interrupt generated
	FSD	Enable and disable First Supply Detection (FSD) interrupt	1: Interrupt generation disabled
	RESET_IN	Enable and disable interrupt from the RESET_IN pin	1: Interrupt generated disabled

Table 8. INT3 OTP Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE
INT3_MASK	VBUS	Interrupt to detect rising or falling VBUS line	1: Interrupt generation disabled
	GPADC_EOC_SW	GPADC result ready from software-initiated conversion	1: Interrupt generation disabled
	GPADC_AUTO_1	GPADC automatic conversion result 1 above or below the reference threshold	0: Interrupt generated
	GPADC_AUTO_0	GPADC automatic conversion result 0 above or below the reference threshold	0: Interrupt generated

Table 9. INT4 OTP Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE
INT4_MASK	GPIO_6	Enable and disable interrupt from the GPIO6 pin rising or falling edge	1: Interrupt generation disabled
	GPIO_5	Enable and disable interrupt from the GPIO5 pin rising or falling edge	1: Interrupt generation disabled
	GPIO_4	Enable and disable interrupt from the GPIO4 pin rising or falling edge	1: Interrupt generation disabled
	GPIO_3	Enable and disable interrupt from the GPIO3 pin rising or falling edge	1: Interrupt generation disabled
	GPIO_2	Enable and disable interrupt from the GPIO2 pin rising or falling edge	1: Interrupt generation disabled
	GPIO_1	Enable and disable interrupt from the GPIO1 pin rising or falling edge	1: Interrupt generation disabled
	GPIO_0	Enable and disable interrupt from the GPIO0 pin rising or falling edge	1: Interrupt generation disabled

5.5 GPIO

TPS65917-Q1 integrates eight configurable general-purpose I/Os (GPIOs) that are multiplexed with alternative features. This section describes the default configuration of each GPIO, as well as the configuration of internal pullup or pulldown resistors on the GPIOs.

Table 10. GPIO Function OTP Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x32 VALUE	0x31, 0x33 VALUE
PRIMARY_SECONDARY_PAD2	GPIO_6	Select pin function	POWERGOOD	NSLEEP
	GPIO_5	Select pin function	POWERHOLD	
	GPIO_4	Select pin function	REGEN2	
PRIMARY_SECONDARY_PAD1	GPIO_3	Select pin function	SYNCDCDC	
	GPIO_2	Select pin function	GPIO_2	
	GPIO_1	Select pin function	NRESWARM	
	GPIO_0	Select pin function	REGEN1	

NOTE: The GPIO_0 pin is an open drain pin and therefore must be pulled up externally. TI does not recommend pulling the GPIO_0 pin up to any always-on signal such as VCCA or LDOVRTC_OUT. The GPIO_0 pin is configured as an input before the OTP memory is loaded at power up, and pulling the pin up to an always-on rail can cause a glitch on the GPIO_0 pin. Therefore, TI recommends pulling this signal up to a sequenced output, such as SMPS3 (1.8 V) or LDO4 (3.3 V).

Table 11 describes the pullup, pulldown, and open-drain settings for the corresponding GPIOs. These settings only apply in GPIO mode (eg. GPIO_0), and do not apply to any of the secondary functions (eg. REGEN1).

Table 11. GPIO Pullup, Pulldown, and Open Drain Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE
PU_PD_GPIO_CTRL2	GPIO_6_PD	Configure pulldown for GPIO_6	0: Pulldown disabled
	GPIO_5_PD	Configure pulldown for GPIO_5	0: Pulldown disabled
	GPIO_4_PU	Configure pullup for GPIO_4	0: Pullup disabled
	GPIO_4_PD	Configure pulldown for GPIO_4	0: Pulldown disabled
PU_PD_GPIO_CTRL1	GPIO_3_PD	Configure pulldown for GPIO_3	1: Pulldown enabled
	GPIO_2_PU	Configure pullup for GPIO_2	1: Pullup enabled
	GPIO_2_PD	Configure pulldown for GPIO_2	0: Pulldown disabled
	GPIO_1_PD	Configure pulldown for GPIO_1	0: Pulldown disabled
	GPIO_0_PD	Configure pulldown for GPIO_0	0: Pulldown disabled
OD_OUTPUT_GPIO	GPIO_4_OD	Configure GPIO_4 to be open-drain or push-pull	0: Push-pull
	GPIO_2_OD	Configure GPIO_2 to be open-drain or push-pull	0: Push-pull

Table 12 describes the polarity settings for each GPIO. These settings apply to both GPIO mode and secondary functions.

Table 12. GPIO Polarity Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE
POLARITY_CTRL	GPIO_6_POLARITY	Enable or disable polarity inversion for GPIO_6	0: Inversion disabled
	GPIO_5_POLARITY	Enable or disable polarity inversion for GPIO_5	0: Inversion disabled
	GPIO_4_POLARITY	Enable or disable polarity inversion for GPIO_4	0: Inversion disabled
	GPIO_3_POLARITY	Enable or disable polarity inversion for GPIO_3	0: Inversion disabled
	GPIO_2_POLARITY	Enable or disable polarity inversion for GPIO_2	0: Inversion disabled
	GPIO_1_POLARITY	Enable or disable polarity inversion for GPIO_1	0: Inversion disabled
	GPIO_0_POLARITY	Enable or disable polarity inversion for GPIO_0	0: Inversion disabled

5.6 MISC

This section describes miscellaneous device configuration settings including pulldowns, polarity of signals, communication settings, and other functionality.

Table 13. MISC1 OTP Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE
PU_PD_INPUT_CTRL1	RESET_IN_PD	Enable and disable internal pulldown for the RESET_IN pin	1: Pulldown enabled
	PWRDOWN_PD	Enable and disable internal pulldown for the PWRDOWN pin	1: Pulldown enabled

Table 14. MISC2 OTP Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE
I2C_SPI	I2C_SPI	Selection of control interface, I^2C, or SPI	0: I^2C
	ID_I2C2	I2C_2 address for page access versus initial address (0H12)	0: Address is 0x12
	ID_I2C1	I2C_1 address for I^2C register access	I2C_1[0] = 1: 0x58 I2C_1[1] = 1: 0x59 I2C_1[2] = 1: 0x5A I2C_1[3] = 1: 0x5B
PMU_CONFIG	HIGH_VCC_SENSE	Enable internal buffers on VCC_SENSE to allow voltage sensing above 5.25 V	0: High VCC sense not enabled
	AUTODEVON	Automatically set DEV_ON bit after startup sequence completes	0: AUTODEVON disabled
	SWOFF_DLY	Delay before switch-off to allow host processor to save context. Device is maintained as ACTIVE until delay expiration then switches off.	00: No delay
PMU_CTRL2	INT_LINE_DIS	Configure INT output to be standard buffer or high-impedance buffer with pullup to VIO	0: Standard buffer: open-drain or push-pull
	WDT_HOLD_IN_SLEEP	Configure watchdog timer operation during device sleep state	0: Watchdog timer continues to run in sleep state
	PWRDOWN_FASTOFF	Configure shut-down sequence from PWRDOWN pin event	0: PWRDOWN pin event triggers sequenced shut down
	TSHUT_FASTOFF	Configure shut-down sequence from thermal shutdown event	0: Thermal shutdown triggers sequenced shut down
OD_OUTPUT_CTRL2	RESET_OUT_OD	Configure RESET_OUT to be push-pull or open-drain	0: RESET_OUT is push-pull
	REGEN2_OD	Configure REGEN2 to be push-pull or open-drain	0: REGEN2 is push-pull
PMU_SECONDARY_INT	FSD_MASK	Secondary level of mask for FSD interrupt line	1: FSD_INT_SRC is masked
POLARITY_CTRL	INT_POLARITY	Configure polarity of INT line	0: INT line is low when interrupt is pending
PRIMARY_SECONDARY_PAD2	SYNCCLKOUT	Configure SYNCCLKOUT to output SYNCDCDCCLK or CLK32KGO	0: SYNCDCDCCLK

5.7 SWOFF_HWRST

This section describes whether each reset type is configured to generate a HWRST or SWORST.

Hardware reset (HWRST) — A hardware reset occurs when any OFF request is configured to generate a hardware reset. This reset triggers a transition to the OFF state from either the ACTIVE or SLEEP state (execute either the ACT2OFF or SLP2OFF sequence).

Switch-off reset (SWORST) — A switch-off reset occurs when any OFF request is configured to not generate a hardware reset. This reset acts as the HWRST, except only the SWO registers are reset. The device enters the OFF state, from either ACTIVE or SLEEP, and therefore executes the ACT2OFF or SLP2OFF sequence.
The power resource control registers for SMPS and LDO voltage levels and operating mode control are in SWORST domain. Additionally some registers control the 32-kHz, REGENx and SYSENx, watchdog, and VSYS_MON comparator. This list is indicative only.

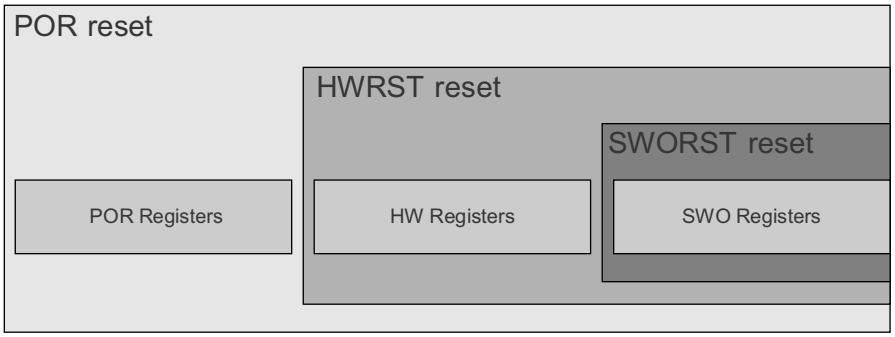

Figure 7. Reset Levels versus Registers

Table 15. SWOFF_HWRST OTP Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE
SWOFF_HWRST	PWRON_LPK	Define if PWRON long key press is causing HWRST or SWORST	1: HWRST
	PWRDOWN	Define if PWRDOWN pin is causing HWRST or SWORST	0: SWORST
	WTD	Define if watchdog expiration is causing HWRST or SWORST	1: HWRST
	TSHUT	Define if thermal shutdown is causing HWRST or SWORST	1: HWRST
	RESET_IN	Define if RESET_IN pin is causing HWRST or SWORST	1: HWRST
	SW_RST	Define if register bit is causing HWRST or SWORST	1: HWRST
	VSYS_LO	Define if VSYS_LO is causing HWRST or SWORST	1: HWRST
	GPADC_SHUTDOWN	Define if GPADC event is causing HWRST or SWORST	0: SWORST

5.8 Shutdown_ColdReset

These OTP settings show whether each OFF request is configured to generate a shutdown request (SD) or cold reset request (CR).

- When configured to generate an SD, the embedded power controller (EPC) executes a transition to the OFF state (SLP2OFF or ACT2OFF power sequence) and remains in the OFF state.
- When configured to generate a CR, the EPC executes a transition to the OFF state (SLP2OFF or ACT2OFF power sequence) and restarts, transitioning to the ACTIVE state (OFF2ACT power sequence) if none of the ON request gating conditions are present.

Table 16. Shutdown_ColdReset OTP Settings

REGISTER	BIT	DESCRIPTION	0x30, 0x31, 0x32, 0x33 VALUE
SWOFF_COLDRST	PWRON_LPK	Define if PWRON long key press causes shutdown or cold reset	0: Shutdown
	PWRDOWN	Define if PWRDOWN pin causes shutdown or cold reset	0: Shutdown
	WTD	Define if watchdog timer expiration causes shutdown or cold reset	1: Cold reset
	TSHUT	Define if thermal shutdown causes shutdown or cold reset	0: Shutdown
	RESET_IN	Define if RESET_IN pin causes shutdown or cold reset	0: Shutdown
	SW_RST	Define if SW_RST register bit causes shutdown or cold reset	1: Cold reset
	VSYS_LO	Define if VSYS_LO causes shutdown or cold reset	0: Shutdown
	GPADC_SHUTDOWN	Define if GPADC shutdown causes shutdown or cold reset	0: Shutdown

6 Sequence Platform Settings

A power sequence is an automatic preprogrammed sequence handled by the TPS65917-Q1 device to configure the device resources: SMPSs, LDOs, part of GPIOs, and REGEN signals into ON, OFF, or SLEEP state.

6.1 OFF2ACT Sequences

When an ON request occurs in the OFF state, the device is switched on and each resource is enabled based on the programmed OFF2ACT sequence.

Figure 8 shows the OFF2ACT sequence of the O917A130TRGZRQ1 and O917A131TRGZRQ1 devices.

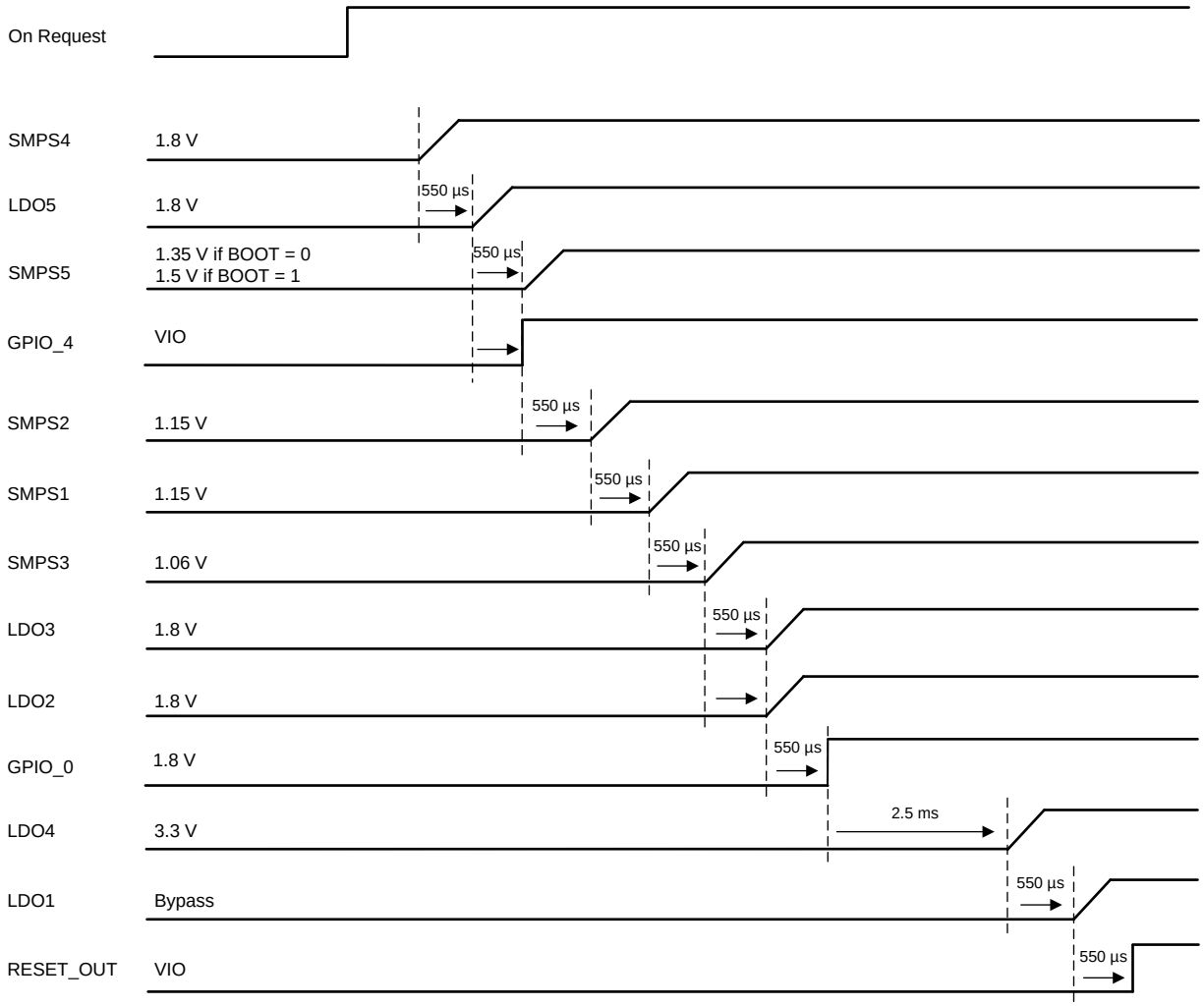

Figure 8. OFF2ACT Sequence of O917A130TRGZRQ1 and O917A131TRGZRQ1

Figure 9 shows the OFF2ACT sequence of O917A132TRGZRQ1 and O917A133TRGZRQ1 devices.

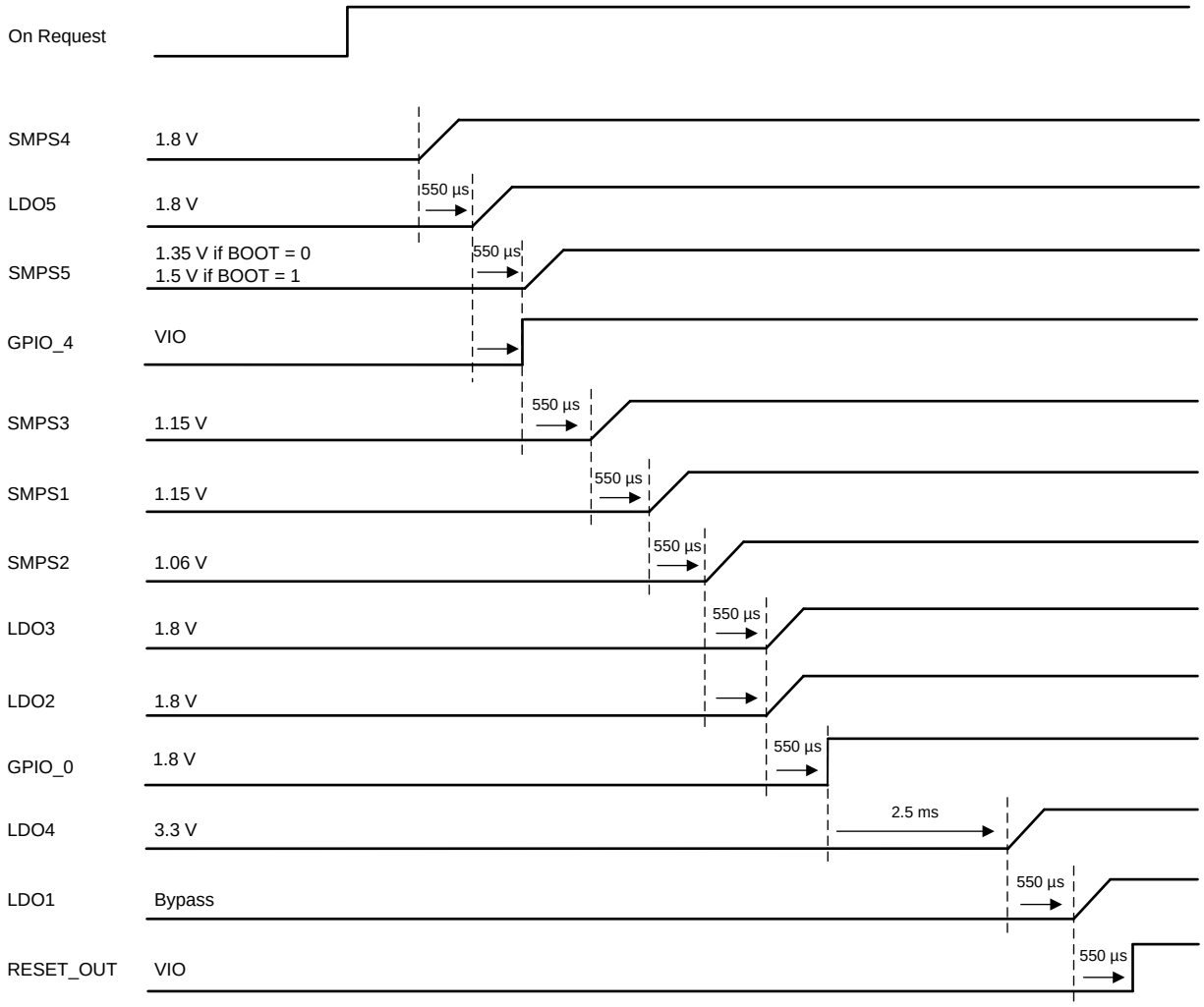

Figure 9. OFF2ACT Sequence of O917A132TRGZRQ1 and O917A133TRGZRQ1

6.2 ACT2OFF Sequences

When an OFF request occurs during active mode, each resource is disabled based on the programmed ACT2OFF sequence.

Figure 10 shows the ACT2OFF sequences of O917A130TRGZRQ1 and O917A131TRGZRQ1 devices.

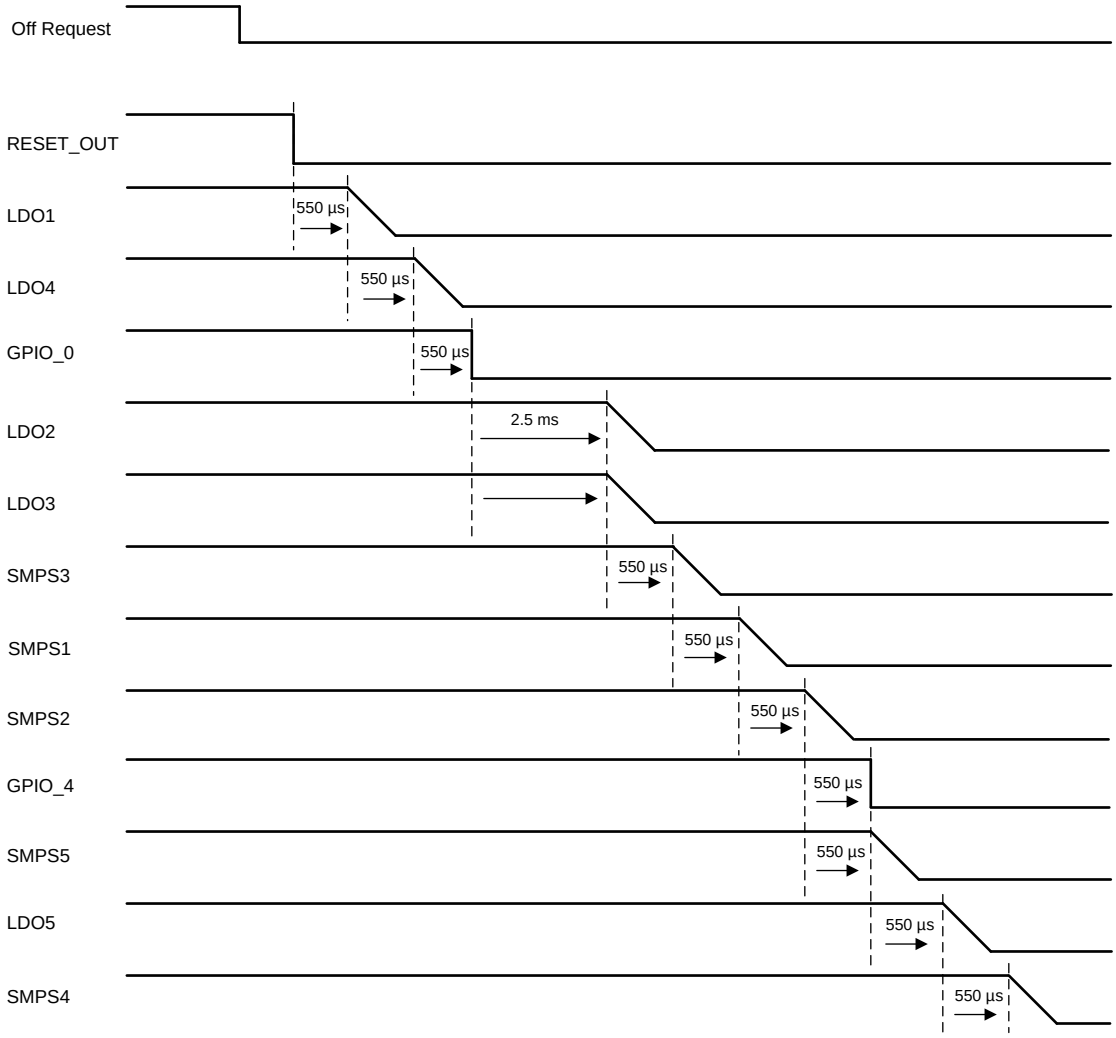

Figure 10. Power Down Sequence of O917A130TRGZRQ1 and O917A131TRGZRQ1

Figure 11 shows the ACT2OFF sequences of O917A132TRGZRQ1 and O917A133TRGZRQ1 devices.

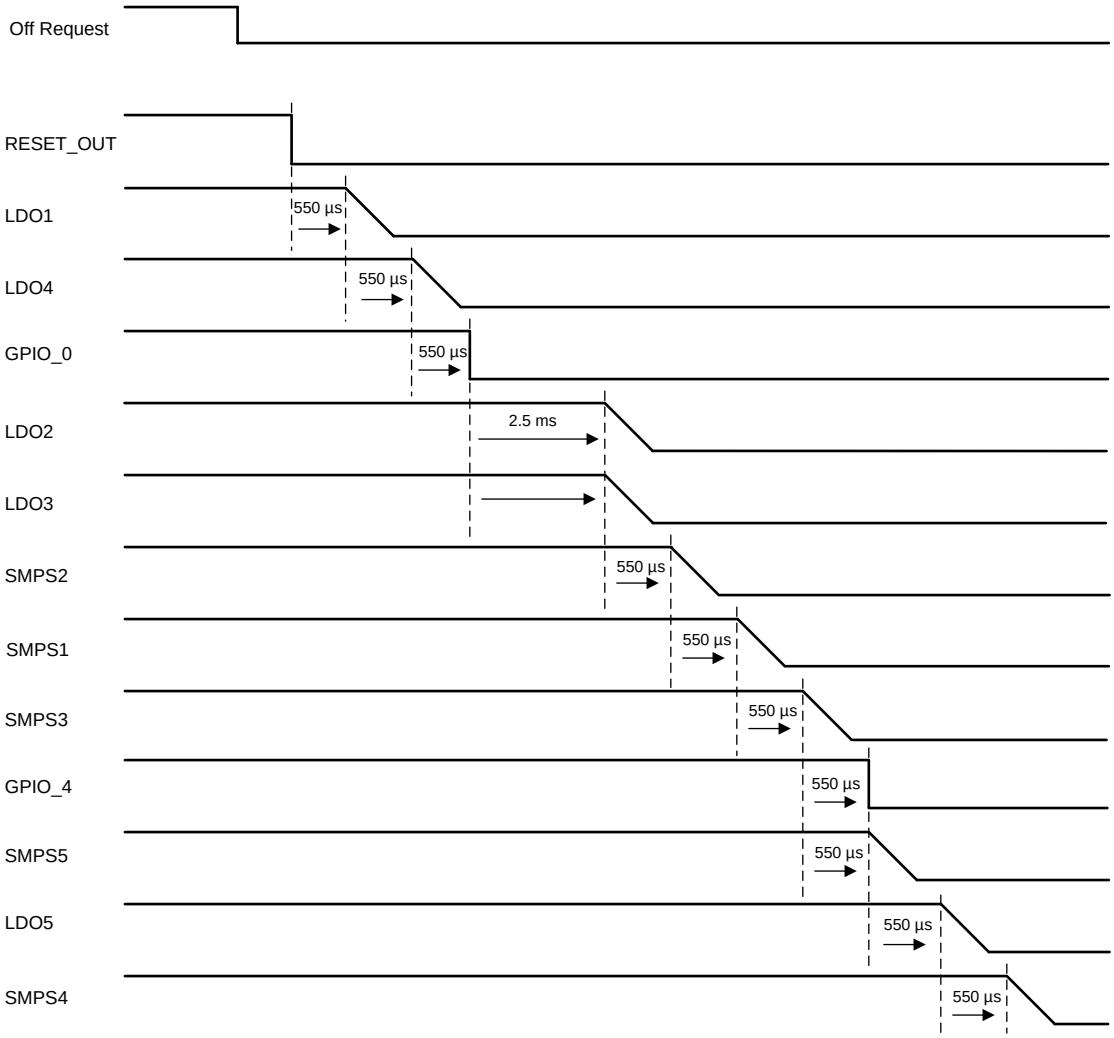

Figure 11. Power Down Sequence of O917A132TRGZRQ1 and O917A133TRGZRQ1

6.3 ACT2SLP and SLP2ACT Sequences

When a SLEEP request occurs during active mode, each resource transitions to the sleep operating mode (MODE_SLEEP bits of the corresponding CTRL register) based on the programmed ACT2SLP sequence. When a WAKE request occurs during sleep mode, each resource transitions to the active operating mode (MODE_ACTIVE bits of the corresponding CTRL register) based on the programmed SLP2ACT sequence. Since OTP versions 0x30 and 0x32 do not have the NSLEEP function selected on GPIO_6, they do not support a sleep sequence.

The sleep sequences of 0x31 and 0x33 are intended to support a DDR self-refresh mode. In this sleep mode, all resources will remain off except for SMPS5 which powers the DDR supply. When using this mode, GPIO_4 should enable a switch between SMPS5 and the processor's DDR domain, so that the processor can be unpowered in DDR self refresh mode by disabling the switch while SMPS5 remains on.

The following five steps must occur before a resource shuts off in sleep mode.

Step 1. Each resource must be set to be OFF in sleep mode by clearing the MODE_SLEEP bits of the appropriate xxxx_CTRL register, for example SMPS1_CTRL register.

Step 2. Each resource must be assigned to NSLEEP through the appropriate NSLEEP_xxxx_ASSIGN registers. For example, the NSLEEP_SMPS_ASSIGN register.

Step 3. The NSLEEP pin must be unmasked through the POWER_CTRL.NSLEEP_MASK register bit

Step 4. All interrupts must be cleared, because any pending interrupt prevents the PMIC from going to sleep mode.

Step 5. A SLEEP request is generated through the NSLEEP pin.

For the OTP versions 0x31 and 0x33 which support a sleep sequence, step 1 is completed in OTP. The control register of each resource in the sleep sequences will have the MODE_SLEEP bits set to "0" after power-up.

Note that RESET_OUT and GPIO_4 are in the VIO domain, and therefore output the same voltage as VIO_IN. When VIO_IN is connected to SMPS4 or a switched 3.3V rail, then RESET_OUT will be shut off during sleep mode at the same time as VIO_IN of the PMIC. If VIO_IN remains supplied during sleep mode, then RESET_OUT will remain high. To keep the processor sequence requirements when using DDR self-refresh mode, VIO_IN should not be disabled until GPIO_4 is turned off in the ACT2SLP sequence, and VIO_IN should be enabled before GPIO_4 is turned on in the SLP2ACT sequence.

Figure 12 shows the ACT2SLP and SLP2ACT sequences of O917A131TRGZRQ1. Figure 13 shows the ACT2SLP and SLP2ACT sequences of O917A133TRGZRQ1.

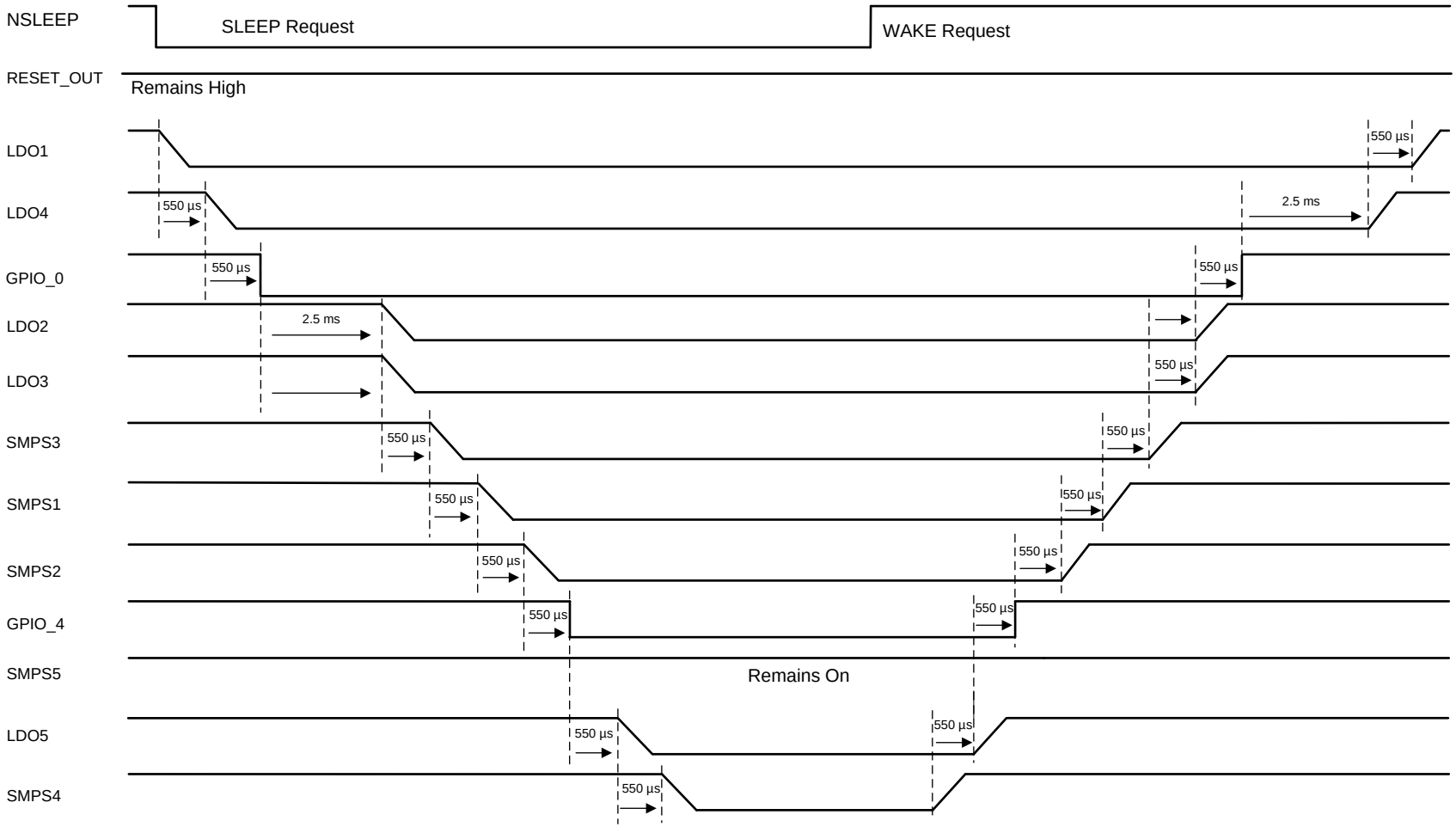

Figure 12. ACT2SLP and SLP2ACT Sequences of O917A131TRGZRQ1

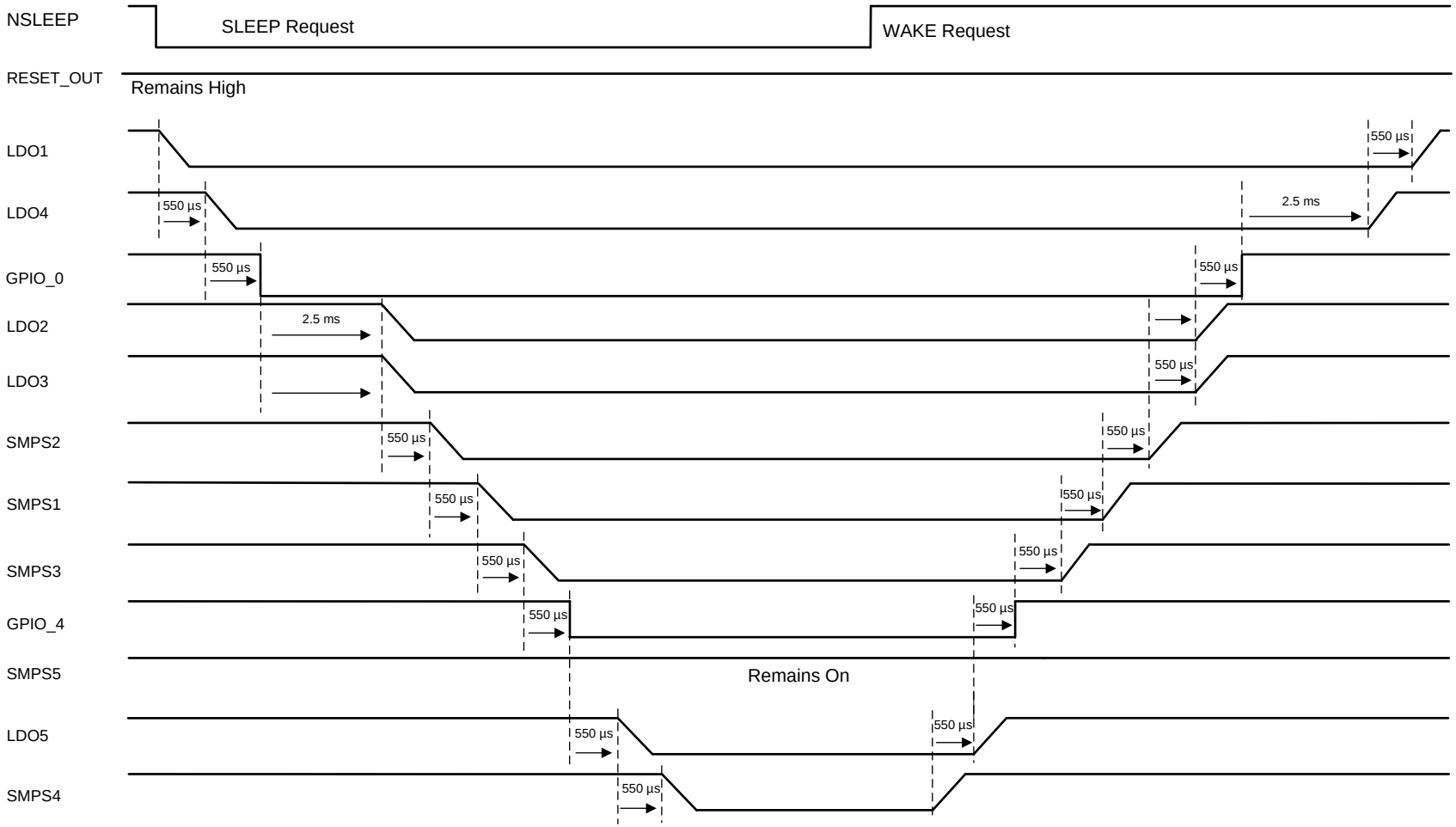

Figure 13. ACT2SLP and SLP2ACT Sequences of O917A133TRGZRQ1

6.4 Warm Reset Sequences

A warm reset is triggered by the NRESWARM pin. During a warm reset, the OFF2ACT sequence is executed regardless of the actual state (ACTIVE, SLEEP) and the device returns to or remains in the ACTIVE state. Resources that are part of power-up sequence go to ACTIVE mode and the output voltage level is reloaded from OTP or kept in the previous value depending on the WR_S bit in the SMPSx_CTRL register or the LDOx_CTRL register. Resources that are not part of the OFF2ACT sequence are not impacted by a warm reset and maintain the previous state.

Additionally, RESET_OUT is asserted low during the warm reset sequence. Therefore the PMIC must be enabled by the POWERHOLD (GPIO_5) pin or by AUTODEVON. If POWERHOLD is set to GND and AUTODEVON is disabled, the PMIC will shut off during the warm reset sequence.

Figure 14 shows the warm reset sequence of O917A130TRGZRQ1 and O917A131TRGZRQ1. If any resource is on when NRESWARM is asserted, the resource remains on as shown by the solid **black** lines. The dashed **red** lines show the timing in case any resource is off before the warm reset. If VIO_IN is switched off before the warm reset sequence, then RESET_OUT and GPIO_4 will be off because they are in the VIO domain. In this example, VIO_IN is supplied by SMPS4, so RESET_OUT follows the SMPS4 timing.

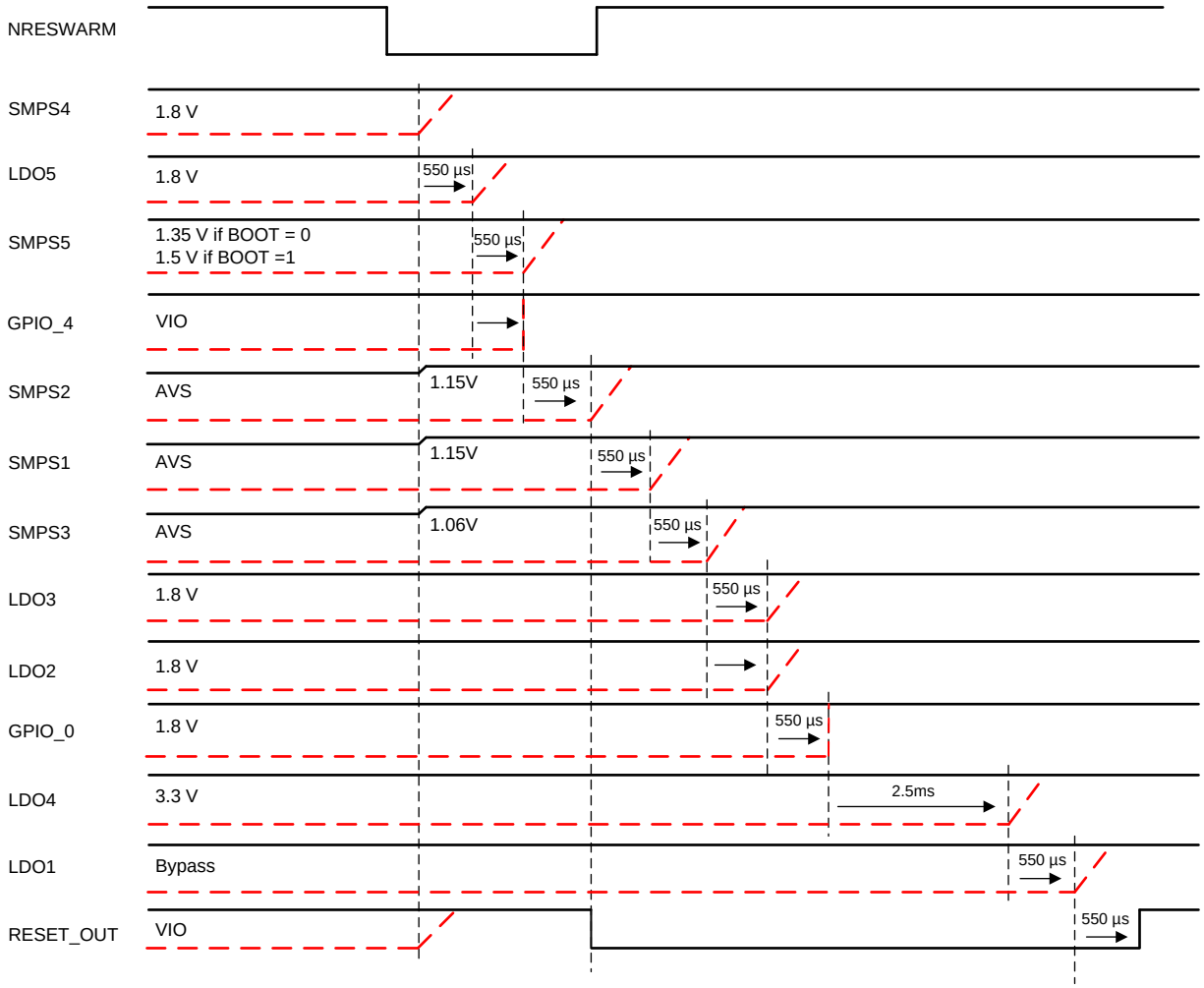

Figure 14. Warm Reset Sequence of O917A130TRGZRQ1 and O917A131TRGZRQ1

Figure 15 shows the warm reset sequence of O917A132TRGZRQ1 and O917A133TRGZRQ1. If any resource is on when NRESWARM is asserted, the resource remains on as shown by the solid **black** lines. The dashed **red** lines show the timing in case any resource is off before the warm reset. If VIO_IN is switched off before the warm reset sequence, then RESET_OUT and GPIO_4 will be off because they are in the VIO domain. In this example, VIO_IN is supplied by SMPS4, so RESET_OUT follows the SMPS4 timing.

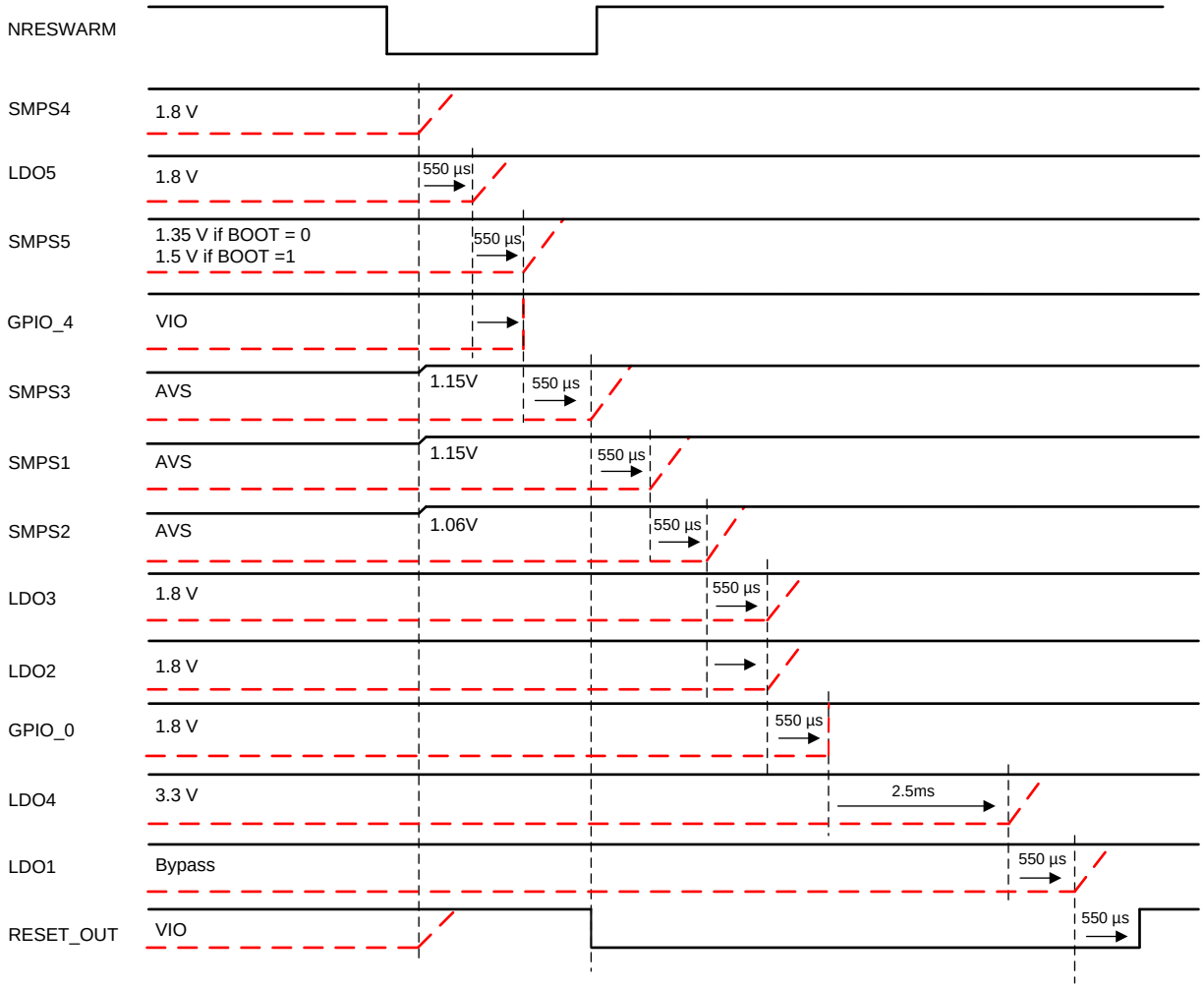

Figure 15. Warm Reset Sequence of O917A132TRGZRQ1 and O917A133TRGZRQ1

Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from E Revision (October 2017) to F Revision **Page**

- Added GPIO_6 function and load current requirements for Jacinto 6 processors in the OTP summary table 2
- Added information and diagrams on the two power up options for the TPS65917-Q1. 5

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Changes from D Revision (July 2017) to E Revision **Page**

- Added GPIO_0 pull-up note 9

Changes from C Revision (March 2017) to D Revision **Page**

- Changed GPIO_3 to be in PRIMARY_SECONDARY_PAD1 register 9

Changes from B Revision (February 2016) to C Revision **Page**

- First public release of document 2

Changes from A Revision (December 2015) to B Revision **Page**

- Updated *System Voltage Monitoring* 6
- Removed reference to VCC_SENSE2 7

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